



Product / Package Information	
Package	LFCSP - Sawn
Body Size (mm)	9 X 9 X 0.75
Lead Count	64
Terminal Finish	100 Sn

Environmental Information	
RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	7.48E-02	84.50	845000	32.80	328010
Thermosets	Epoxy & Phenol Resin	Proprietary	1.33E-02	15.00	150000	5.82	58227
Other inorganic materials	Carbon black	1333-86-4	4.43E-04	0.50	5000	0.19	1941
Subtotal			8.85 E-02	100.00	1000000	38.82	388177

Leadframe							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.21 E-01	97.5	975000	53.19	531923
Copper & its alloys	Iron	7439-89-6	2.92 E-03	2.35	23500	1.28	12821
Copper & its alloys	Zinc	7440-66-6	1.49 E-04	0.12	1200	0.07	655
Copper & its alloys	Phosphorus	7723-14-0	3.73 E-05	0.03	300	0.02	164
Subtotal			1.24 E-01	100.00	1000000	54.56	545562

Internal Leadframe Plating							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.24 E-03	100.0	1000000	0.55	5456

External Leadframe Plating							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.52 E-03	100.0	1000000	1.11	11050

Bond Wires							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	9.30 E-04	99.00	990000	0.41	4081
Precious metals	Palladium	7440-05-3	9.40 E-06	1.00	10000	0.004	41
Subtotal			9.40 E-04	100.0	1000000	0.41	4122

Chip							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	9.09 E-03	100.0	1000000	3.99	39882

Die Attach							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.01 E-03	77.00	770000	0.44	4428
Other organic materials	Acrylic resin	Proprietary	9.18 E-05	7.00	70000	0.04	403
Other organic materials	Acrylate	Proprietary	7.21 E-05	5.50	55000	0.03	316
Other organic materials	Polybutadiene derivative	Proprietary	5.90 E-05	4.50	45000	0.03	259
Other organic materials	Epoxy resin	Proprietary	3.28 E-05	2.50	25000	0.01	144
Other organic materials	Butadiene Copolymer	Proprietary	1.97 E-05	1.50	15000	0.01	86
Others	Additive	Proprietary	1.97 E-05	1.50	15000	0.01	86
Others	Peroxide	Proprietary	6.56 E-06	0.50	5000	0.003	29
Subtotal			1.31 E-03	100.0	1000000	0.58	5751

Package Totals				Weight (g)	Percentage (%)	PPM
				2.28 E-01	100	1000000

Control ID:MS012306 PKG5353
Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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